

RCX200N20

Nch 200V 20A Power MOSFET

| V_{DSS} | 200V |
|----------------------------|----------|
| R _{DS(on)} (Max.) | 130m $Ω$ |
| I _D | 20A |
| P_D | 48W |

Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Drive circuits can be simple.
- 4) Parallel use is easy.
- 5) Pb-free lead plating; RoHS compliant
- 6) 100% Avalanche tested

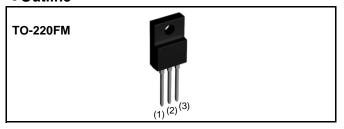
Application

Switching Power Supply

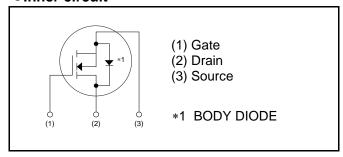
Automotive Motor Drive

Automotive Solenoid Drive

Outline



•Inner circuit



Packaging specifications

| | Packaging | Bulk |
|------|-----------------|-----------|
| | Reel size (mm) | - |
| Type | Tape width (mm) | - |
| Туре | Quantity (pcs) | 500 |
| | Taping code | - |
| | Marking | RCX200N20 |

● Absolute maximum ratings(T_a = 25°C)

| Parameter | Symbol | Value | Unit | |
|---------------------------------------|-------------------------|--------------------|-------|----|
| Drain - Source voltage | V _{DSS} | 200 | V | |
| Continuous drain current | T _c = 25°C | I _D *1 | ±20 | А |
| | T _c = 100°C | I _D *1 | ±10.8 | А |
| Pulsed drain current | I _{D,pulse} *2 | ±80 | А | |
| Gate - Source voltage | V_{GSS} | ±30 | V | |
| Avalanche energy, single pulse | | E _{AS} *3 | 32.3 | mJ |
| Avalanche current | | I _{AR} *3 | 10 | А |
| $T_c = 25^{\circ}C$ | | P _D | 48 | W |
| Power dissipation $T_a = 25^{\circ}C$ | | P _D | 2.23 | W |
| Junction temperature | | Tj | 150 | °C |
| Range of storage temperature | T _{stg} | -55 to +150 | °C | |

●Thermal resistance

| Parameter | Symbol | Values | | | Unit |
|--|-------------------|--------|------|------|-------|
| - Farameter | Symbol | Min. | Тур. | Max. | Offic |
| Thermal resistance, junction - case | R_{thJC} | - | - | 2.57 | °C/W |
| Thermal resistance, junction - ambient | R_{thJA} | - | - | 56 | °C/W |
| Soldering temperature, wavesoldering for 10s | T _{sold} | - | - | 265 | °C |

•Electrical characteristics($T_a = 25$ °C)

| Parameter | Symbol | Conditions | Values | | | Unit |
|---|------------------------|---|--------|------|------|-------|
| Parameter | Symbol | Conditions | Min. | Тур. | Max. | Offic |
| Drain - Source breakdown voltage | $V_{(BR)DSS}$ | $V_{GS} = 0V$, $I_D = 1mA$ | 200 | - | - | V |
| | | $V_{DS} = 200V, V_{GS} = 0V$ $T_i = 25^{\circ}C$ | - | - | 25 | |
| Zero gate voltage drain current | I _{DSS} | $V_{DS} = 200V, V_{GS} = 0V$ $T_j = 125^{\circ}C$ | - | - | 100 | μА |
| Gate - Source leakage current | I _{GSS} | $V_{GS} = \pm 30V, V_{DS} = 0V$ | - | - | ±100 | nA |
| Gate threshold voltage | V _{GS (th)} | $V_{DS} = 10V$, $I_D = 1mA$ | 3.0 | - | 5.0 | V |
| | | $V_{GS} = 10V, I_D = 10A$ | - | 100 | 130 | |
| Static drain - source on - state resistance | R _{DS(on)} *4 | $V_{GS} = 10V, I_{D} = 10A$ $T_{j} = 125^{\circ}C$ | - | 220 | 310 | mΩ |
| Forward transfer admittance | g fs | $V_{DS} = 10V, I_{D} = 10A$ | 4.9 | 9.8 | - | S |

•Electrical characteristics($T_a = 25$ °C)

| Parameter | Symbol | Conditions | Values | | | Unit |
|------------------------------|------------------------|------------------------------------|--------|------|------|-------|
| r arameter | Symbol Conditions | | Min. | Тур. | Max. | Offic |
| Input capacitance | C _{iss} | $V_{GS} = 0V$ | ı | 1900 | ı | |
| Output capacitance | C_{oss} | V _{DS} = 25V | - | 120 | 1 | pF |
| Reverse transfer capacitance | C_{rss} | f = 1MHz | - | 70 | 1 | |
| Turn - on delay time | t _{d(on)} *4 | $V_{DD} \simeq 100V, V_{GS} = 10V$ | - | 35 | 1 | |
| Rise time | t _r *4 | I _D = 10A | - | 100 | - | nc |
| Turn - off delay time | t _{d(off)} *4 | $R_L = 10\Omega$ | - | 60 | - | ns |
| Fall time | t _f *4 | $R_G = 10\Omega$ | - | 45 | - | |

•Gate Charge characteristics($T_a = 25$ °C)

| Parameter | Symbol | Conditions | Values | | | Unit |
|----------------------|------------------------|------------------------------------|--------|------|------|-------|
| Parameter | Symbol | ol Conditions - | | Тур. | Max. | Offic |
| Total gate charge | Q_g^{*4} | V _{DD} ≃ 100V | - | 40 | - | |
| Gate - Source charge | Q _{gs} *4 | I _D = 10A | - | 15 | 1 | nC |
| Gate - Drain charge | ${\sf Q_{gd}}^{^{*4}}$ | V _{GS} = 10V | - | 15 | 1 | |
| Gate plateau voltage | V _(plateau) | $V_{DD} \simeq 100V$, $I_D = 10A$ | - | 8.0 | - | V |

●Body diode electrical characteristics (Source-Drain)(T_a = 25°C)

| Parameter | Cymbol | Conditions | Values | | | Unit |
|---------------------------|--------------------|----------------------------|--------|------|------|-------|
| Parameter | Symbol | Conditions | Min. | Тур. | Max. | Offic |
| Continuous source current | l _S *1 | T _c = 25°C | - | - | 20 | Α |
| Pulsed source current | I _{SM} *2 | 1 _c = 23 C | - | - | 80 | А |
| Forward voltage | V_{SD}^{*4} | $V_{GS} = 0V, I_{S} = 20A$ | - | - | 1.5 | V |
| Reverse recovery time | t _{rr} *4 | I _S = 10A | - | 100 | - | ns |
| Reverse recovery charge | Q _{rr} *4 | di/dt = 100A/μs | - | 350 | - | nC |

^{*1} Limited only by maximum temperature allowed.

^{*2} Pw \leq 10 μ s, Duty cycle \leq 1%

^{*3} L $^{\simeq}$ 500 μ H, V_{DD} = 50V, Rg = 25 Ω , starting T $_{j}$ = 25°C

^{*4} Pulsed

Fig.1 Power Dissipation Derating Curve

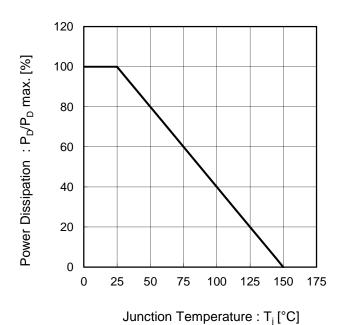
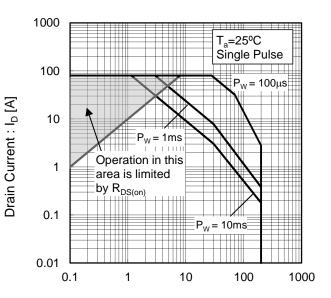
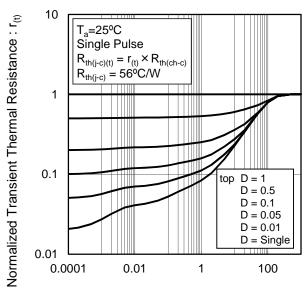


Fig.2 Maximum Safe Operating Area



Drain - Source Voltage : V_{DS} [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width



Pulse Width : $P_W[s]$

Fig.4 Avalanche Current vs Inductive Load

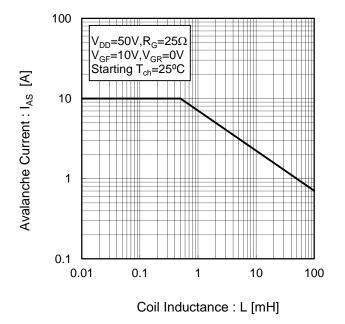
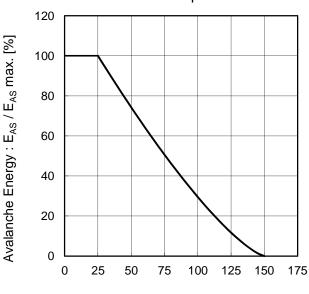
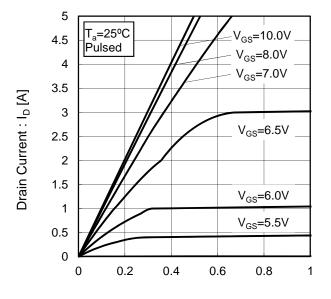


Fig.5 Avalanche Energy Derating Curve vs Junction Temperature



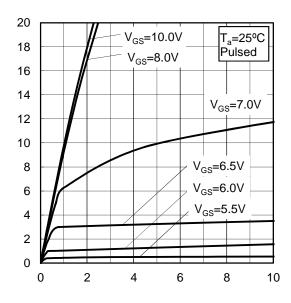
Junction Temperature : T_i [°C]

Fig.6 Typical Output Characteristics(I)



Drain - Source Voltage : V_{DS} [V]

Fig.7 Typical Output Characteristics(II)



Drain - Source Voltage : V_{DS} [V]

Drain Current: I_D [A]

Fig.8 Breakdown Voltage vs. Junction Temperature 280 Normarize Drain - Source Breakdown Voltage $V_{GS} = 0V$ 270 $I_D = 1mA$ 260 250 240 230 220 210 200 190 180 -50 0 50 100 150 Junction Temperature : T_i [°C]

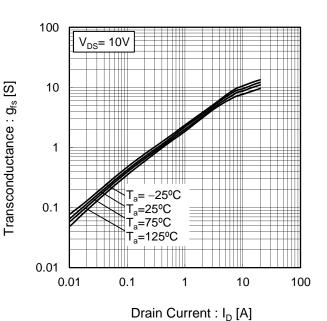
100 $V_{DS} = 10V$ 10 Drain Current: I_D [A] T_a= 125°C T_a= 75°C T_a= 25°C 0.1 T_a= -25°C 0.01 0.001 0 1 2 3 4 5 6 7 8 9 10

Fig.9 Typical Transfer Characteristics

Fig.10 Gate Threshold Voltage vs. Junction Temperature 5.0 $V_{DS} = 10V$ $I_D = 1 \text{mA}$ Gate Threshold Voltage: V_{GS(th)} [V] 4.5 4.0 3.5 3.0 2.5 -50 -25 25 50 75 100 125 150 Junction Temperature : T_i [°C]

Fig.11 Transconductance vs. Drain Current

Gate - Source Voltage : V_{GS} [V]



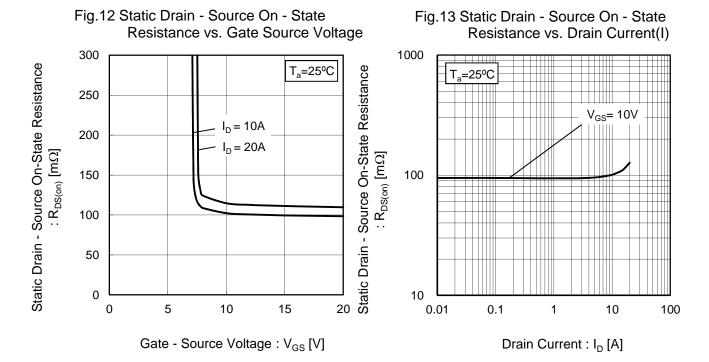


Fig.14 Static Drain - Source On - State Resistance vs. Junction Temperature

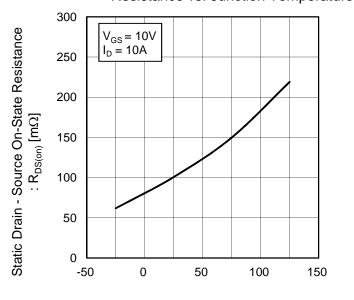


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current(II)

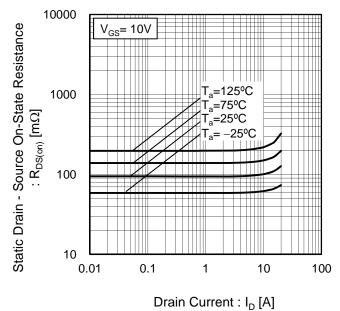
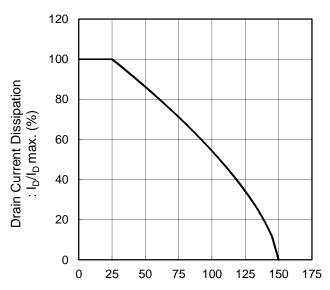
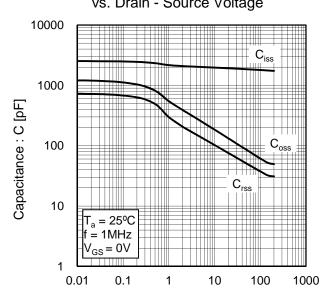


Fig.16 Drain Current Derating Curve



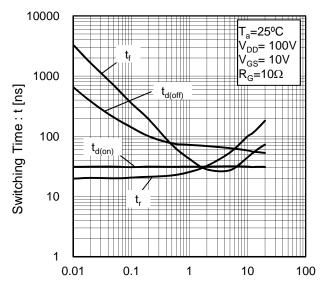
Junction Temperature : T_i [°C]

Fig.17 Typical Capacitance vs. Drain - Source Voltage



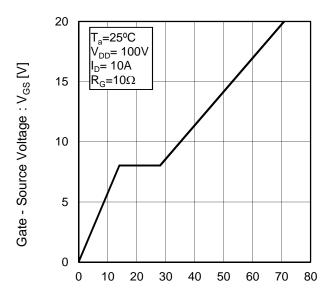
Drain - Source Voltage : V_{DS} [V]

Fig.18 Switching Characteristics

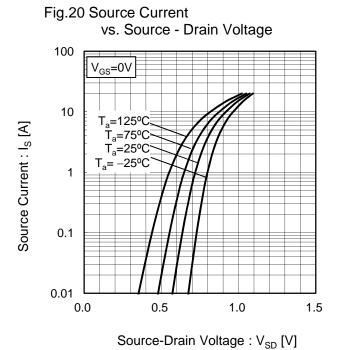


Drain Current : I_D [A]

Fig.19 Dynamic Input Characteristics



Total Gate Charge : Q_g [nC]



Vs. Source Current

1000

T_a=25°C

di / dt = 100A / μs

V_{GS} = 0V

100

0.1

1 10 100

Source Current : I_S [A]

Fig21 Reverse Recovery Time

●Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

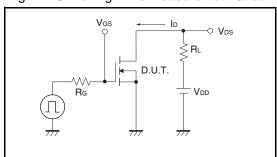


Fig.2-1 Gate Charge Measurement Circuit

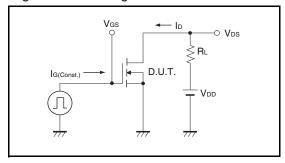


Fig.3-1 Avalanche Measurement Circuit

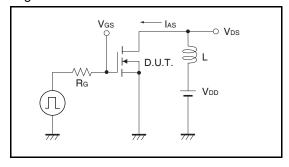


Fig.1-2 Switching Waveforms

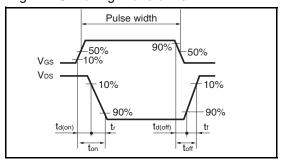


Fig.2-2 Gate Charge Waveform

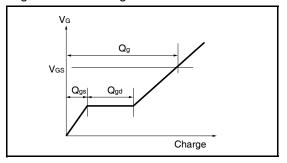
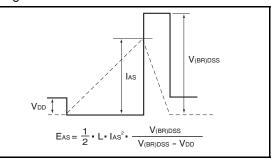
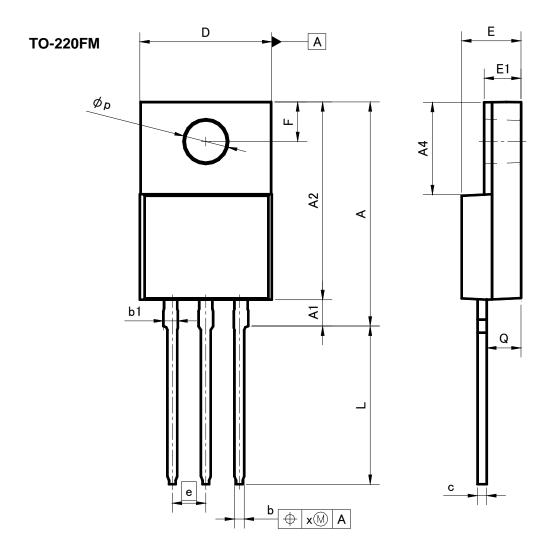


Fig.3-2 Avalanche Waveform



●Dimensions (Unit : mm)



| DIM | MILIMETERS | | INC | HES |
|-----|------------|-------|-------|-------|
| DIM | MIN | MAX | MIN | MAX |
| Α | 16.60 | 17.60 | 0.654 | 0.693 |
| A1 | 1.80 | 2.20 | 0.071 | 0.087 |
| A2 | 14.80 | 15.40 | 0.583 | 0.606 |
| A4 | 6.80 | 7.20 | 0.268 | 0.283 |
| b | 0.70 | 0.85 | 0.028 | 0.033 |
| b1 | 1.10 | 1.50 | 0.043 | 0.059 |
| С | 0.70 | 0.85 | 0.028 | 0.033 |
| D | 9.90 | 10.30 | 0.39 | 0.406 |
| Е | 4.40 | 4.80 | 0.173 | 0.189 |
| е | 2.54 | | 0. | 10 |
| E1 | 2.70 | 3.00 | 0.106 | 0.118 |
| F | 2.80 | 3.20 | 0.11 | 0.126 |
| L | 11.50 | 12.50 | 0.453 | 0.492 |
| р | 3.00 | 3.40 | 0.118 | 0.134 |
| Q | 2.10 | 3.10 | 0.083 | 0.122 |
| X | _ | 0.381 | _ | 0.015 |

Dimension in mm/inches

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|---------|--------|------------|-----------|
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| CLASSIV | CLASSⅢ | CLASSⅢ | CLASSⅢ |

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 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
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- 8. Confirm that operation temperature is within the specified range described in the product specification.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
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